



Material Content Data Sheet



Sales Product Name		TLS835B2EL V		Issued		3. October 2018		
MA#		MA001728824						
Package		PG-SSOP-14-5		Weight*		82.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.221	1.48	1.48	14764	14764
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		417	
	non noble metal	iron	7439-89-6	0.689	0.83		8331	
wire	non noble metal	copper	7440-50-8	27.978	33.83	34.71	338291	347143
	non noble metal	copper	7440-50-8	0.044	0.05	0.05	537	537
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1222
encapsulation	plastics	epoxy resin	-	4.649	5.62		56215	
	inorganic material	silicondioxide	60676-86-0	45.784	55.36	61.10	553595	611032
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11803	11803
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9282	9282
glue	plastics	epoxy resin	-	0.112	0.14		1360	
	noble metal	silver	7440-22-4	0.337	0.41	0.55	4079	5439
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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